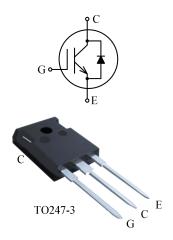


IGBT in advanced TrenchFS Technology with soft and fast recovery anti-parallel diode 具有先进 TrenchFS 技术的 IGBT 且反并联软快恢复二极管

Features:

特性

- 650V TrenchFS technology 650V 沟槽栅场终止技术
- Low conduction and switching losses 低导通和开关损耗
- Positive temperature coefficient 饱和电压正温度系数
- Short Circuit withstand time-5μs 具备5μs短路承受能力



Applications:

应用

- PFC 功率因数校正
- General Inverter 通用变频器

Type	V _{CE} [V]	I _C [A]	V _{CEsat} [V]	T _{jmax} [℃]	Marking	Package
型号	集电极-发射极电压	集电极电流	饱和电压	最高结温	标记	封装
BGN30T65SD	650	30	1.6	175	30T65SD	TO247-3



Maximum Rated Values

最大额定参数

Parameter 参数	Symbol 符号	Value 值	Unit 单位
Collector-emitter voltage, T _j ≥25℃ 集电极-发射极电压,T _j ≥25℃	$ m V_{CE}$	650	V
Collector current,T _C =25℃ 集电极电流,T _C =25℃	Ic	60	
Collector current,T _C =100℃ 集电极电流,T _C =100℃	I_{C}	30	
Pulsed collector current, t_p limited by $T_{j \text{ max}}$ 集电极脉冲电流,脉宽时间受 $T_{j \text{ max}}$ 限制	I_{Cpuls}	120	A
Diode forward current, T _C =25℃ 二极管正向电流,Tc=25℃	I_{F}	60	A
Diode forward current, T _C =100℃ 二极管正向电流,T _C =100℃	I_{F}	30	
Diode pulsed current 二极管脉冲电流	I_{Fpuls}	120	
Gate-emitter voltage 栅极-发射极电压	$V_{ m GE}$	±20	V
Short Circuit withstand time V _{GE} =15V,V _{CC} ≤400V,T _j ≤150℃ 短路耐受时间	$t_{ m sc}$	5	us
Total power dissipation, T _C =25℃ 总耗散功率,T _C =25℃	P _{tot}	238	W
Operating junction temperature 最高结温	$T_{ m jmax}$	175	
Operating junction temperature 工作结温	$T_{ m jop}$	-40+150	${\mathbb C}$
Storage temperature 储存温度	$T_{ m stg}$	-55+150	C
Soldering temperature,1.6mm from case for 10s 焊接温度	T _{st}	260	
Mounting Torque M3 锁装力矩	Md	0.6	Nm

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Thermal Resistance

热阻

Parameter 参数	Symbol 符号	Value 值	Unit 单位
IGBT Thermal resistance junction to case IGBT 结-管壳热阻	$R_{\text{th(j-c)}}$	0.65	°C/W
Diode Thermal resistance junction to case 二极管结-管壳热阻	$R_{\text{th(j-c)}}$	1.69	°C/W
Thermal resistance junction to ambient 结-环境热阻	$R_{th(j-a)}$	40	°C/W

Electrical Characteristic at $Tj = 25^{\circ}C$ (unless otherwise specified)

Tj=25℃时电学特性(除非特别声明)

			\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	Value		
Parameter	Symbol	Conditions		值		TT */
参数	符号	条件	Min. 最小 值	Typ. 典型 值	Max. 最大 值	Unit 単位

Static Characteristic

静态特性

11. 10.14 1工							
Collector-emitter breakdown voltage 集电极-发射极击穿电压	V _{(BR)CES}	V _{GE} =0V, I _C =100uA		650	-	-	
Collector-emitter saturation voltage 集电极-发射极饱和电压	Voeset	Vcesat $V_{GE}=15V$, $I_{C}=30A$	T _j =25℃	-	1.6	2.0	
	v cesat		T _j =150℃	-	1.8	-	V
Diode forward voltage	VF	$V_{\rm F}$ $V_{\rm GE}$ =0 $V_{\rm r}$ $I_{\rm F}$ =30 A	T _j =25℃	-	1.7	2.5	V
二极管正向电压			T _j =150℃	-	1.4	-	
Gate-emitter threshold voltage 栅极-发射极阈值电压	V _{GE(th)}	I _C =300uA, V _{CE} =V _{GE}		5.0	5.8	7.0	
Collector-emitter cut-off current 集电极-发射极截止电流	I _{CES}	V_{CE} =650V, V_{GE} =0V		-	-	100	μА
Gate-emitter leakage current 栅极-发射极漏电流	I _{GES}	$V_{CE}=0V,$ $V_{GE}=\pm 20V$		-200	-	200	nA

Dynamic Characteristic

动态特性

Input capacitance 输入电容	Cies		-	1800	-	
Output capacitance 输出电容	Coes	$V_{CE}=25V$, $V_{GE}=0V$,	-	158	-	pF
Reverse transfer capacitance 反向传输电容	Cres	f=1MHz	-	51.7	-	

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Gate charge 门极电量	Q _G	V _{CC} =400V,I _C =30A, V _{GE} =15V	-	63.9	-	nC
Short circuit current 短路电流	I _{C(sc)}	V_{CC} =400V, V_{GE} =15V, tpsc \leq 5us, T_{j} =150°C	-	120	-	A

Switching Characteristic at $T_j = 25^{\circ}\mathbb{C}$ (Inductive Load)

Tj=25℃时开关特性(感性负载)

Parameter	Symbol 符号	Conditions	Value 值			
参数		Septiments 条件	Min. 最小 值	Typ. 典型 值	Max. 最大 值	Unit 単位
IGBT Characteristic IGBT 特性						1
Turn-on delay time 开通延迟时间	t _{d(on)}		-	47	-	
Rise time 上升时间	$t_{\rm r}$	T _j =25℃,	-	62	-	
Turn-off delay time 关断延迟时间	$t_{d(off)}$	V_{CC} =400V, I_{C} =30A,	-	95	-	ns
Fall time 下降时间	t_{f}	V_{GE} =-7.5/15V, R_{G} =10 Ω ,	-	154	-	
Turn-on energy 开通损耗	Eon	Energy losses include "tail" and diode	-	0.97	-	
Turn-off energy 关断损耗	E _{off}	reverse recovery.	-	0.45	-	mJ
Total switching energy 总开关损耗	E _{ts}		-	1.42	-	
Anti-Parallel Diode Characteristic 反并联二极管特性	;		·			
Reverse recovery time 反向恢复时间	t _{rr}	T _j =25℃,	-	136	-	ns
Recovered charge 恢复电荷	Qr	V_R =400V, I_F =30A,	-	78	-	nC
Peak reverse recovery current 反向恢复峰值电流	I_{RM}	diF/dt=390A/μs	-	7.6	-	A

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Switching Characteristic at T_j =150°C (Inductive Load)

Tj=150℃时开关特性(感性负载)

P	Symbol 符号	G IV	Value 值			
Parameter 参数		Conditions 条件	Min. 最小 值	Typ. 典型 值	Max. 最大 值	Unit 単位
IGBT Characteristic IGBT 特性						
Turn-on delay time 开通延迟时间	t _{d(on)}		-	46	-	
Rise time 上升时间	t _r	T _j =150°C,	-	61	-	
Turn-off delay time 关断延迟时间	$t_{d(off)}$	V_{CC} =400V, I_{C} =30A, V_{GE} =-7.5/15V, R_{G} =10 Ω , Energy losses include "tail" and diode	-	111	-	ns
Fall time 下降时间	t_{f}		-	141	-	
Turn-on energy 开通损耗	Eon		-	1.27	-	
Turn-off energy 关断损耗	E _{off}	reverse recovery.	-	0.72	-	mJ
Total switching energy 总开关损耗	E_{ts}		-	1.99	-	
Anti-Parallel Diode Characteristic 反并联二极管特性	:		·			
Reverse recovery time 反向恢复时间	t _{rr}	Tj=150°C,	-	208	-	ns
Recovered charge 恢复电荷	Qr	V_R =400V, I_F =30A, diF/dt =400A/ μ s	-	680	-	nC
Peak reverse recovery current 反向恢复峰值电流	I_{RM}		-	13.4	-	A

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ELECTRICAL CHARACTERISTICS 特性曲线

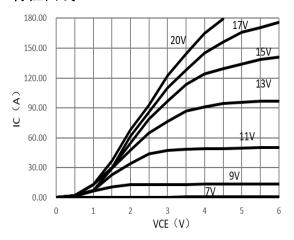


Figure 1. Typical output characteristic(T_j=25℃)

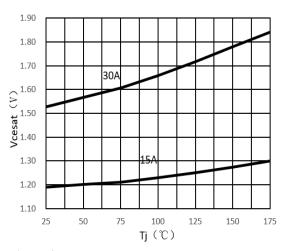


Figure 3. V_{cesat} vs. T_j

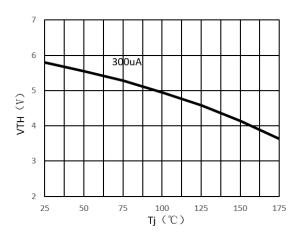


Figure 5. V_{TH} vs. T_j

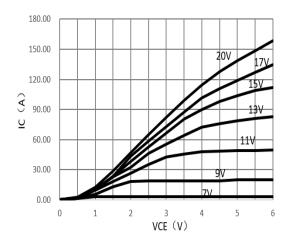


Figure 2. Typical output characteristic($T_j=150$ °C)

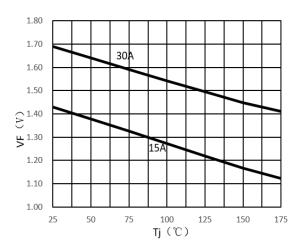


Figure 4. V_F vs. T_j

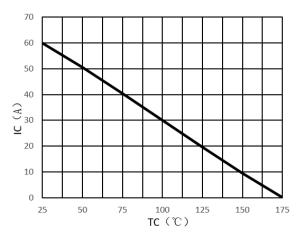


Figure 6. I_C VS T_C



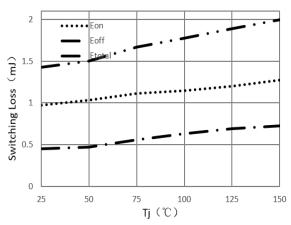


Figure 7. Switching energy losses vs T_j (V_{CE} =400V, V_{GE} =15V, I_C =30A, R_G =10 Ω)

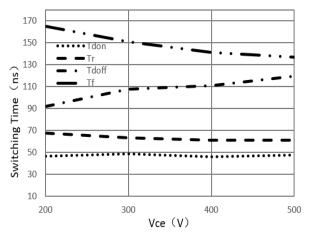


Figure 9. Switching times vs V_{CE} ($T_j{=}150\,^{\circ}\!C$, $V_{GE}{=}15V_{,}I_{C}{=}30A_{,}R_{G}{=}10\,\Omega$)

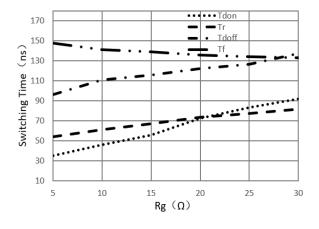
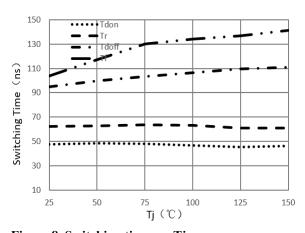


Figure 11. Switching times vs R_g (T_j =150°C, V_{CE} =400V, V_{GE} =15V, I_C =30A)



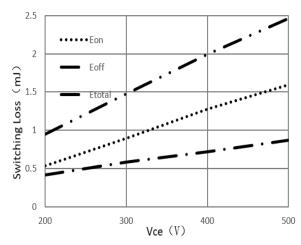


Figure 10. Switching energy losses vs V_{CE} (T_j =150 $^{\circ}$ C, V_{CE} =400 V, V_{GE} =15 V, I_C =30 A)

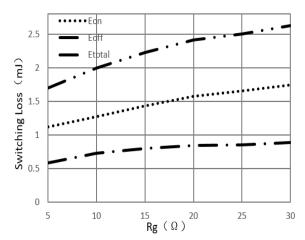
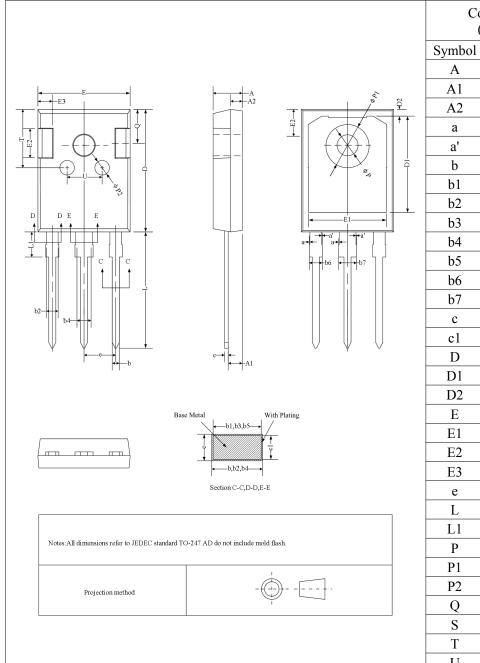


Figure 12. Switching energy losses vs R_g (T_j =150°C, V_{CE} =400V, V_{GE} =15V, I_C =30A)



TO247-3 Outline Dimensions:

TO247-3 外形尺寸



Common Dimensions (Units:Millimeter)							
Min.	Nom.	Max.					
4.90	5.00	5.10					
2.31	2.41	2.51					
1.90	2.00	2.10					
0.00	-	0.15					
0.00	-	0.15					
1.16	-	1.26					
1.15	1.20	1.22					
1.96	-	2.06					
1.95	2.00	2.02					
2.96	-	3.06					
2.95	3.00	3.02					
-	-	2.25					
-	-	3.25					
0.59	-	0.66					
0.58	0.60	0.62					
20.90	21.00	21.10					
16.25	16.55	16.85					
1.05	1.20	1.35					
15.70	15.80	15.90					
13.10	13.30	13.50					
4.90	5.00	5.10					
2.40	2.50	2.60					
5.34	5.44	5.54					
19.80	19.92	20.10					
-	-	4.30					
3.50	3.60	3.70					
_	-	7.40					
2.40	2.50	2.60					
5.60	-	6.00					
6.05	6.15	6.25					
9.80	-	10.20					
6.00	-	6.40					
	Units:Mi Min. 4.90 2.31 1.90 0.00 0.00 1.16 1.15 1.96 1.95 2.96 2.95 - 0.59 0.58 20.90 16.25 1.05 15.70 13.10 4.90 2.40 5.34 19.80 - 3.50 - 2.40 5.60 6.05 9.80	Min. Nom. 4.90 5.00 2.31 2.41 1.90 2.00 0.00 - 0.00 - 1.16 - 1.15 1.20 1.96 - 1.95 2.00 2.96 - 2.95 3.00 - - 0.59 - 0.58 0.60 20.90 21.00 16.25 16.55 1.05 1.20 15.70 15.80 13.10 13.30 4.90 5.00 2.40 2.50 5.34 5.44 19.80 19.92 - - 2.40 2.50 5.60 - 6.05 6.15 9.80 -					

Packing

包装

Packing	pcs/tube	tube/ inner box	inner box/ carton	pcs/carton
Tube	30	12	6	2160

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- The information contained herein is subject to change without notice.
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